

PATENT ASSIGNMENT

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Chen-Han Lin	07/28/2011
Hong-Da Chang	07/28/2011
Cheng-Hsiang Liu	07/28/2011
Hsin-Yi Liao	07/28/2011
Shih-Kuang Chiu	07/28/2011
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Siliconware Precision Industries Co., Ltd.
<b>Street Address:</b>	No. 123, Sec. 3, Da Fong Road, Tantzou
<b>City:</b>	Taichung
<b>State/Country:</b>	TAIWAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	13314807
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	89796(71987)
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<b>Total Attachments: 1</b> source=89796_Assignment#page1.tif	

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# ASSIGNMENT OF U.S. PATENT APPLICATION

In consideration of the sum of One Dollar in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned

Inventor(s) 1. Chen-Han LIN 2. Hong-Da CHANG  
Full Name(s) 3. Cheng-Hsiang LIU 4. Hsin-Yi LIAO  
5. Shih-Kuang CHIU

Hereby sell, assign and transfer to

Assignee SILICONWARE PRECISION INDUSTRIES CO., LTD.  
Name and Address No. 123, Sec. 3, Da Fong Road, Tantz, Taichung, Taiwan, R.O.C.

(hereinafter called the Assignee) the entire right, title, and interest in and to any and all improvements which are disclosed in the Application for United States Letters Patent entitled

Title of Invention: METHOD FOR FABRICATING PACKAGE STRUCTURE HAVING MEMS ELEMENTS

Which application was

Complete either - a) executed by the undersigned on \_\_\_\_\_  
b) filed on the \_\_\_\_\_  
Serial No. \_\_\_\_\_

Including any and all United States Letters Patents which may be granted therefore and any and all extensions, divisions, reissues, substitutes, renewals or continuations thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property.

It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said assignee.

Further, it is agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, renewal, and reissue patent applications; execute all rightful other papers; and generally do everything possible which said Assignee shall consider desirable for aiding in securing and maintaining proper patent protection.

Date Signed at TAIWAN, R.O.C.  
On July 28, 2011

Inventor(s)	<u>Chen-Han LIN</u>	<u>Chen-Han LIN</u>
Full Signature(s)	<u>Hong-Da Chang</u>	<u>Hong-Da CHANG</u>
	<u>Cheng-Hsiang Liu</u>	<u>Cheng-Hsiang LIU</u>
	<u>Hsin-Yi LIAO</u>	<u>Hsin-Yi LIAO</u>
	<u>Shih-Kuang Chiu</u>	<u>Shih-Kuang CHIU</u>

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